

# POSITIVE-VOLTAGE REGULATORS

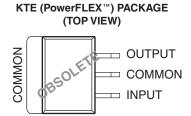
#### **FEATURES**

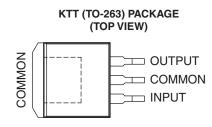
- 3-Terminal Regulators
- Output Current up to 1.5 A
- Internal Thermal-Overload Protection



- Internal Short-Circuit Current Limiting
- Output Transistor Safe-Area Compensation







## **DESCRIPTION/ORDERING INFORMATION**

This series of fixed-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators can deliver up to 1.5 A of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents, and also can be used as the power-pass element in precision regulators.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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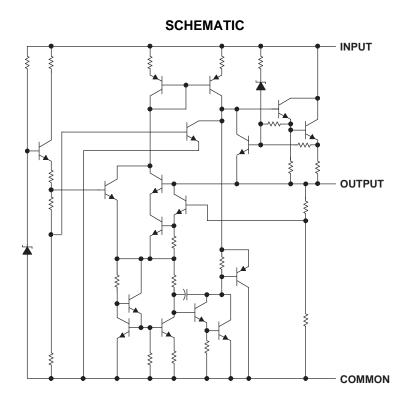
# ORDERING INFORMATION(1)

TJ	V <sub>O(NOM)</sub>	PACKAGE <sup>(2</sup>	)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
		TO-220, short shoulder – KCS	Tube of 50	UA7805CKCS	UA7805C
	5 V	TO-263 – KTT	Reel of 500	UA7805CKTTR	UA7805C
	3 V	PowerFLEX™ – KTE		OBSOLETE	OBSOLETE
		TO-220 – KC		OBSOLETE	OBSOLETE
		TO-220, short shoulder – KCS	Tube of 50	UA7808CKCS	UA7808C
	8 V	TO-263 – KTT	Reel of 500	UA7808CKTTR	UA7808C
	O V	PowerFLEX – KTE		OBSOLETE	OBSOLETE
		TO-220 – KC		OBSOLETE	OBSOLETE
		TO-220, short shoulder – KCS	Tube of 50	UA7810CKCS	UA7810C
	10 V	TO-263 – KTT	Reel of 500	UA7810CKTTR	UA7810C
	10 V	PowerFLEX – KTE		OBSOLETE	OBSOLETE
0°C to 125°C		TO-220 – KC		OBSOLETE	OBSOLETE
0 0 10 125 0		TO-220, short shoulder – KCS	Tube of 50	UA7812CKCS	UA7812C
	12 V	TO-263 – KTT	Reel of 500	UA7812CKTTR	UA7812C
	12 V	PowerFLEX – KTE		OBSOLETE	OBSOLETE
		TO-220 – KC		OBSOLETE	OBSOLETE
		TO-220, short shoulder – KCS	Tube of 50	UA7815CKCS	UA7815C
	15 V	TO-263 – KTT	Reel of 500	UA7815CKTTR	UA7815C
	15 V	PowerFLEX – KTE		OBSOLETE	OBSOLETE
		TO-220 – KC		OBSOLETE	OBSOLETE
		TO-220, short shoulder – KCS	Tube of 50	UA7824CKCS	UA7824C
	24 V	TO-263 – KTT	Reel of 500	UA7824CKTTR	UA7824C
	24 V	PowerFLEX – KTE		OBSOLETE	OBSOLETE
l		TO-220 – KC		OBSOLETE	OBSOLETE

<sup>(1)</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

<sup>(2)</sup> Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.





# Absolute Maximum Ratings<sup>(1)</sup>

over virtual junction temperature range (unless otherwise noted)

			MIN	MAX	UNIT
.,	Input voltogo	μA7824C		40	V
VI	Input voltage All others			35	V
TJ	Operating virtual junction temperature			150	°C
	Lead temperature	1,6 mm (1/16 in) from case for 10 s		260	°C
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

# Package Thermal Data(1)

PACKAGE	BOARD	$\theta_{JA}$	θЈС	θ <sub>JP</sub> <sup>(2)</sup>
PowerFLEX (KTE) – OBSOLETE	High K, JESD 51-5	23°C/W	3°C/W	2.7°C/W
TO-220 (KCS) (KC – OBSOLETE)	High K, JESD 51-5	19°C/W	17°C/W	3°C/W
TO-263 (KTT)	High K, JESD 51-5	25.3°C/W	18°C/W	1.94°C/W

Maximum power dissipation is a function of  $T_{J(max)}$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_{J(max)} - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability. For packages with exposed thermal pads, such as QFN, PowerPAD<sup>TM</sup>, or PowerFLEX,  $\theta_{JP}$  is defined as the thermal resistance between the die junction and the bottom of the exposed pad.





# **Recommended Operating Conditions**

			MIN	MAX	UNIT
	μΑ7805	7	25		
		μΑ7808	10.5	25	
	lanut valta na	μΑ7810	12.5	28	\ /
V <sub>I</sub>	Input voltage	μΑ7812	14.5	30	V
		μΑ7815	17.5	30	
		μΑ7824	27	38	
Io	Output current	<u>.</u>		1.5	Α
TJ	Operating virtual junction temperature		0	125	°C



#### uA7805 Electrical Characteristics

at specified virtual junction temperature,  $V_1 = 10 \text{ V}$ ,  $I_0 = 500 \text{ mA}$  (unless otherwise noted)

DADAMETED	TEST COMPITIONS	<b>T</b> (1)	μ	A7805C		LINUT
PARAMETER	TEST CONDITIONS	T <sub>J</sub> <sup>(1)</sup>	MIN	TYP	MAX	UNIT
Output valtage	$I_0 = 5 \text{ mA to } 1 \text{ A}, V_1 = 7 \text{ V to } 20 \text{ V},$	25°C	4.8	5	5.2	V
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	4.75		5.25	V
lanut valtage regulation	V <sub>I</sub> = 7 V to 25 V	25°C		3	100	mV
Input voltage regulation	V <sub>I</sub> = 8 V to 12 V	25 C		1	50	IIIV
Ripple rejection	V <sub>I</sub> = 8 V to 12 V, f = 120 Hz	0°C to 125°C	62	78		dB
Output voltage regulation	I <sub>O</sub> = 5 mA to 1.5 A	25°C		15	100	.,
	I <sub>O</sub> = 250 mA to 750 mA	25 C		5	50	mV
Output resistance	f = 1 kHz	0°C to 125°C		0.017		Ω
Temperature coefficient of output voltage	$I_O = 5 \text{ mA}$	0°C to 125°C		-1.1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		40		μV
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V
Bias current		25°C		4.2	8	mA
Diag ourrent change	V <sub>I</sub> = 7 V to 25 V	0°C to 125°C			1.3	A
Bias current change	I <sub>O</sub> = 5 mA to 1 A	0.0 10 125.0	0.5		mA mA	
Short-circuit output current		25°C		750		mA
Peak output current		25°C		2.2		Α

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output.

#### **uA7808 Electrical Characteristics**

at specified virtual junction temperature,  $V_1$  = 14 V,  $I_O$  = 500 mA (unless otherwise noted)

DADAMETER	TEST COMPITIONS	T,(1)	μ	A7808C		UNIT	
PARAMETER	TEST CONDITIONS	1,1,1	MIN	TYP	MAX	UNII	
Output valtage	$I_O = 5 \text{ mA to 1 A}, V_I = 10.5 \text{ V to 23 V},$	25°C	7.7	8	8.3	V	
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	7.6		8.4	V	
Input voltage regulation	V <sub>I</sub> = 10.5 V to 25 V	25°C		6	160	mV	
Tiput voltage regulation	V <sub>I</sub> = 11 V to 17 V	25°C		2	80	mv	
Ripple rejection	V <sub>I</sub> = 11.5 V to 21.5 V, f = 120 Hz	0°C to 125°C	55	72		dB	
Output voltage regulation	I <sub>O</sub> = 5 mA to 1.5 A	25°C		12	160	mV	
Output voltage regulation	$I_O = 250 \text{ mA to } 750 \text{ mA}$	25 C		4	80	IIIV	
Output resistance	f = 1 kHz	0°C to 125°C		0.016		Ω	
Temperature coefficient of output voltage	I <sub>O</sub> = 5 mA	0°C to 125°C		-0.8		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz	25°C		52		μV	
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V	
Bias current		25°C		4.3	8	mA	
Diag ourrent change	V <sub>I</sub> = 10.5 V to 25 V	0°C to 125°C			1	mA	
Bias current change	I <sub>O</sub> = 5 mA to 1 A	0.0 10 125.0			0.5	MA	
Short-circuit output current		25°C		450		mA	
Peak output current		25°C		2.2		Α	

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output.



#### uA7810 Electrical Characteristics

at specified virtual junction temperature,  $V_1 = 17 \text{ V}$ ,  $I_0 = 500 \text{ mA}$  (unless otherwise noted)

DADAMETED	TEST CONDITIONS	T,,(1)	μ	A7810C		UNIT
PARAMETER	TEST CONDITIONS	1,1,1,	MIN	TYP	MAX	UNIT
Output voltage	$I_O = 5$ mA to 1 A, $V_I = 12.5$ V to 25 V,	25°C	9.6	10	10.4	V
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	9.5		10.5	V
Input voltage regulation	V <sub>I</sub> = 12.5 V to 28 V	25°C		7	200	mV
Tiput voltage regulation	V <sub>I</sub> = 14 V to 20 V	25 C		2	100	IIIV
Ripple rejection	V <sub>I</sub> = 13 V to 23 V, f = 120 Hz	0°C to 125°C	55	71		dB
Output voltage regulation	I <sub>O</sub> = 5 mA to 1.5 A	25°C		12	200	
	I <sub>O</sub> = 250 mA to 750 mA	25 C		4	100	mV
Output resistance	f = 1 kHz	0°C to 125°C		0.018		Ω
Temperature coefficient of output voltage	$I_O = 5 \text{ mA}$	0°C to 125°C		-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		70		μV
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		٧
Bias current		25°C		4.3	8	mA
Bias current change	V <sub>I</sub> = 12.5 V to 28 V	0°C to 125°C			1	mA
bias current change	$I_O = 5$ mA to 1 A	0 C to 125 C			0.5	ША
Short-circuit output current		25°C		400		mA
Peak output current		25°C		2.2		Α

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output.

#### uA7812 Electrical Characteristics

at specified virtual junction temperature,  $V_I = 19 \text{ V}$ ,  $I_O = 500 \text{ mA}$  (unless otherwise noted)

DADAMETER	TEST CONDITIONS	T,1 <sup>(1)</sup>	μ <b>Α7812C</b>			UNIT	
PARAMETER	TEST CONDITIONS	1,1,1,	MIN	TYP	MAX	UNII	
Output voltage	$I_O = 5 \text{ mA to 1 A}, V_I = 14.5 \text{ V to 27 V},$	25°C	11.5	12	12.5	V	
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	11.4		12.6	V	
Input valtage regulation	V <sub>I</sub> = 14.5 V to 30 V	25°C		10	240	mV	
Input voltage regulation	V <sub>I</sub> = 16 V to 22 V	25 0		3	120	IIIV	
Ripple rejection	V <sub>I</sub> = 15 V to 25 V, f = 120 Hz	0°C to 125°C	55	71		dB	
Output valtage regulation	I <sub>O</sub> = 5 mA to 1.5 A	25°C		12	240	mV	
Output voltage regulation	$I_O = 250 \text{ mA to } 750 \text{ mA}$	25 C		4	120	111 V	
Output resistance	f = 1 kHz	0°C to 125°C		0.018		Ω	
Temperature coefficient of output voltage	$I_O = 5 \text{ mA}$	0°C to 125°C		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz	25°C		75		μV	
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V	
Bias current		25°C		4.3	8	mA	
Pigg gurrent change	V <sub>I</sub> = 14.5 V to 30 V	0°C to 125°C			1	mA	
Bias current change	$I_O = 5$ mA to 1 A	0 C to 125 C			0.5	IIIA	
Short-circuit output current		25°C		350		mA	
Peak output current		25°C		2.2		Α	

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output.



#### **uA7815 Electrical Characteristics**

at specified virtual junction temperature,  $V_1 = 23 \text{ V}$ ,  $I_0 = 500 \text{ mA}$  (unless otherwise noted)

DADAMETED	TEST CONDITIONS	T,1 <sup>(1)</sup>	μ	A7815C		UNIT	
PARAMETER	TEST CONDITIONS	1,1,1	MIN	TYP	MAX	UNII	
Output voltage	$I_O = 5$ mA to 1 A, $V_I = 17.5$ V to 30 V,	25°C	14.4	15	15.6	V	
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	14.25		15.75		
Input voltage regulation	V <sub>I</sub> = 17.5 V to 30 V	25°C		11	300	mV	
Input voltage regulation	V <sub>I</sub> = 20 V to 26 V	25 C		3	150	IIIV	
Ripple rejection	V <sub>I</sub> = 18.5 V to 28.5 V, f = 120 Hz	0°C to 125°C	54	70		dB	
Output valtage regulation	I <sub>O</sub> = 5 mA to 1.5 A	25°C		12	300	>/	
Output voltage regulation	I <sub>O</sub> = 250 mA to 750 mA	25°C		4	150	mV	
Output resistance	f = 1 kHz	0°C to 125°C		0.019		Ω	
Temperature coefficient of output voltage	$I_O = 5 \text{ mA}$	0°C to 125°C		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz	25°C		90		μV	
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V	
Bias current		25°C		4.4	8	mA	
Bias current change	V <sub>I</sub> = 17.5 V to 30 V	0°C to 125°C			1	mA	
bias current change	$I_O = 5$ mA to 1 A	0 C to 125 C			0.5	IIIA	
Short-circuit output current		25°C		230		mA	
Peak output current		25°C		2.1		Α	

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output.

#### **uA7824 Electrical Characteristics**

at specified virtual junction temperature,  $V_1 = 33 \text{ V}$ ,  $I_0 = 500 \text{ mA}$  (unless otherwise noted)

DADAMETER	TEST CONDITIONS	T.,(1)	μ	A7824C		UNIT
PARAMETER	TEST CONDITIONS	IJ'''	MIN	TYP	MAX	UNII
Output valtage	$I_0 = 5 \text{ mA to } 1 \text{ A}, V_1 = 27 \text{ V to } 38 \text{ V},$	25°C	23	24	25	V
Output voltage	P <sub>D</sub> ≤ 15 W	0°C to 125°C	22.8		25.2	V
Input valtage regulation	$V_1 = 27 \text{ V to } 38 \text{ V}$	25°C		18	480	mV
Input voltage regulation	$V_1 = 30 \text{ V to } 36 \text{ V}$	25 C		6	240	IIIV
Ripple rejection	V <sub>I</sub> = 28 V to 38 V, f = 120 Hz	0°C to 125°C	50	66		dB
Output voltage regulation	I <sub>O</sub> = 5 mA to 1.5 A	25°C		12	480	mV
	$I_{O}$ = 250 mA to 750 mA	25 C		4	240	IIIV
Output resistance	f = 1 kHz	0°C to 125°C		0.028		Ω
Temperature coefficient of output voltage	$I_O = 5 \text{ mA}$	0°C to 125°C		-1.5		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz	25°C		170		μV
Dropout voltage	I <sub>O</sub> = 1 A	25°C		2		V
Bias current		25°C		4.6	8	mA
Pigg gurrent change	$V_1 = 27 \text{ V to } 38 \text{ V}$	0°C to 125°C			1	mA
Bias current change	$I_O = 5$ mA to 1 A	0 0 10 125 0			0.5	IIIA
Short-circuit output current		25°C		150		mA
Peak output current		25°C		2.1		Α

<sup>(1)</sup> Pulse-testing techniques maintain the junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output.



## **APPLICATION INFORMATION**

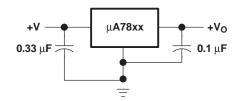


Figure 1. Fixed-Output Regulator

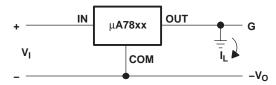
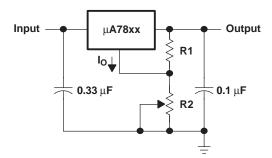


Figure 2. Positive Regulator in Negative Configuration (V<sub>I</sub> Must Float)



A: The following formula is used when  $V_{xx}$  is the nominal output voltage (output to common) of the fixed regulator:

$$V_{O} = V_{xx} + \left(\frac{V_{xx}}{R1} + I_{Q}\right)R2$$

Figure 3. Adjustable-Output Regulator

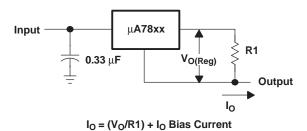


Figure 4. Current Regulator



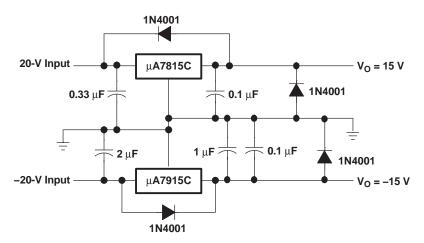


Figure 5. Regulated Dual Supply

## Operation With a Load Common to a Voltage of Opposite Polarity

In many cases, a regulator powers a load that is not connected to ground but, instead, is connected to a voltage source of opposite polarity (e.g., operational amplifiers, level-shifting circuits, etc.). In these cases, a clamp diode should be connected to the regulator output as shown in Figure 6. This protects the regulator from output polarity reversals during startup and short-circuit operation.

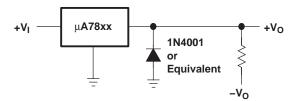


Figure 6. Output Polarity-Reversal-Protection Circuit

#### **Reverse-Bias Protection**

Occasionally, the input voltage to the regulator can collapse faster than the output voltage. This can occur, for example, when the input supply is crowbarred during an output overvoltage condition. If the output voltage is greater than approximately 7 V, the emitter-base junction of the series-pass element (internal or external) could break down and be damaged. To prevent this, a diode shunt can be used as shown in Figure 7.

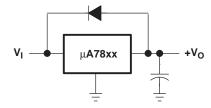


Figure 7. Reverse-Bias-Protection Circuit



# **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
UA7805CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7805CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7805CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7805CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7805CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7805CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR
UA7805CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR
UA7805QKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7805QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7808CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7808CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7808CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7808CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7808CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7808CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR
UA7808CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR
UA7808QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7810CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7810CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7810CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7810CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7810CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7810CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR
UA7810CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR
UA7810QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7812CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7812CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7812CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7812CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7812CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7812CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 HR
UA7812CKTTRG3	ACTIVE	DDPAK/	KTT	3	500	Green (RoHS &	CU SN	Level-3-245C-168 HR





com 12-Jan-2009

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup> L	.ead/Ball Finis	h MSL Peak Temp <sup>(3</sup>
		TO-263				no Sb/Br)		
UA7812QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7815CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7815CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7815CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7815CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7815CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 H
UA7815CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 H
UA7815QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7824CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7824CKCE3	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7824CKCS	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7824CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA7824CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7824CKTTR	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 H
UA7824CKTTRG3	ACTIVE	DDPAK/ TO-263	KTT	3	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-245C-168 H
UA7885CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA7885CKTER	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI
UA7885QKTE	OBSOLETE	PFM	KTE	3		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# **PACKAGE OPTION ADDENDUM**

12-Jan-2009

accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

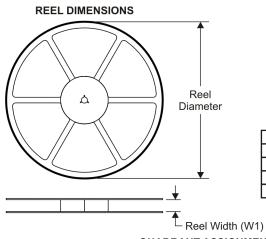
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.





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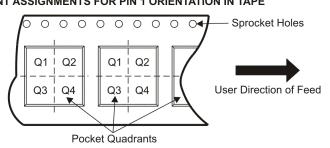
## TAPE AND REEL INFORMATION



# TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

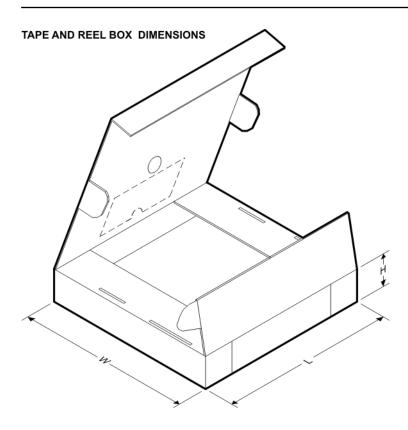
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA7805CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
UA7808CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
UA7810CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
UA7812CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
UA7815CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2
UA7824CKTTR	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.6	15.8	4.9	16.0	24.0	Q2



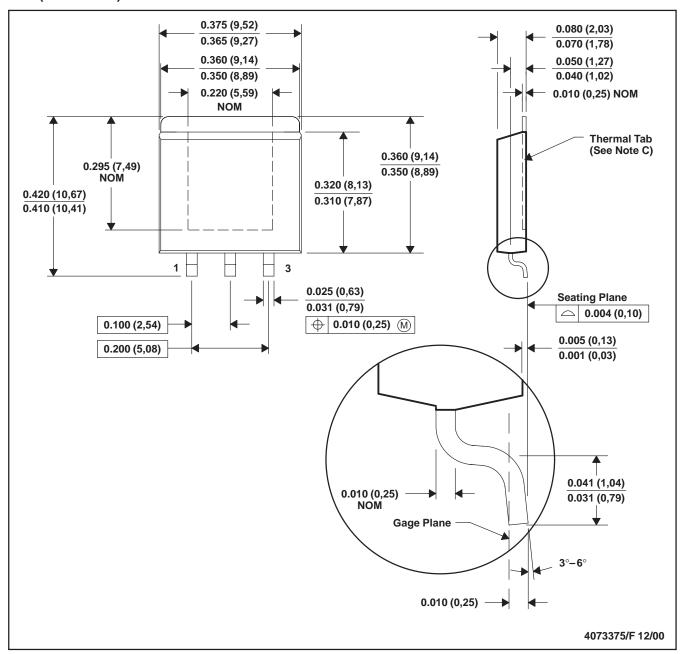


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA7805CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7808CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7810CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7812CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7815CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
UA7824CKTTR	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0

## KTE (R-PSFM-G3)

#### **PowerFLEX™ PLASTIC FLANGE-MOUNT**



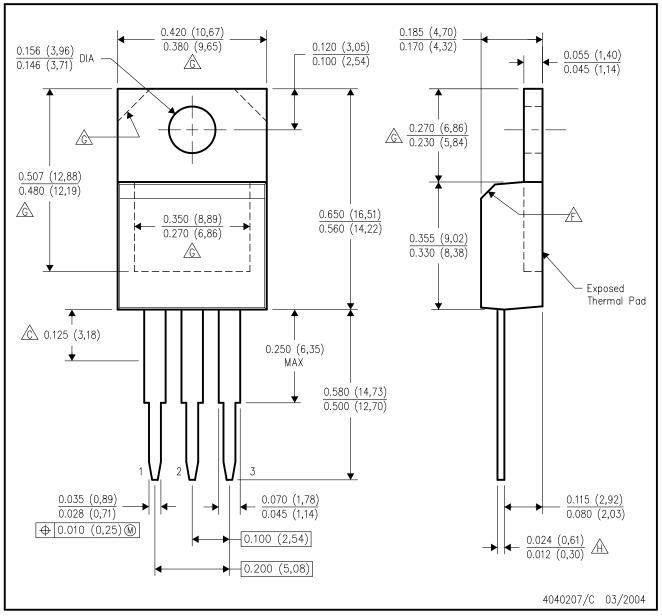
- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. The center lead is in electrical contact with the thermal tab.
  - D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
  - E. Falls within JEDEC MO-169

PowerFLEX is a trademark of Texas Instruments.



# KC (R-PSFM-T3)

# PLASTIC FLANGE-MOUNT PACKAGE



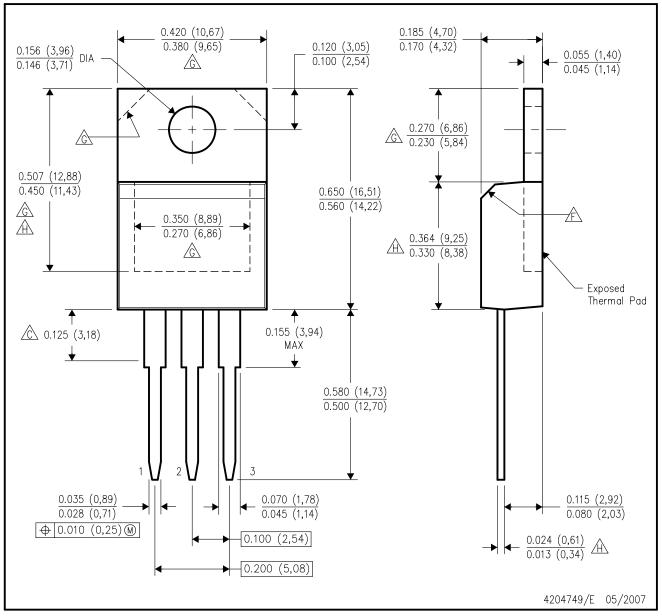
NOTES: A. All linear

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC TO-220 variation AB, except minimum lead thickness.



# KCS (R-PSFM-T3)

# PLASTIC FLANGE-MOUNT PACKAGE



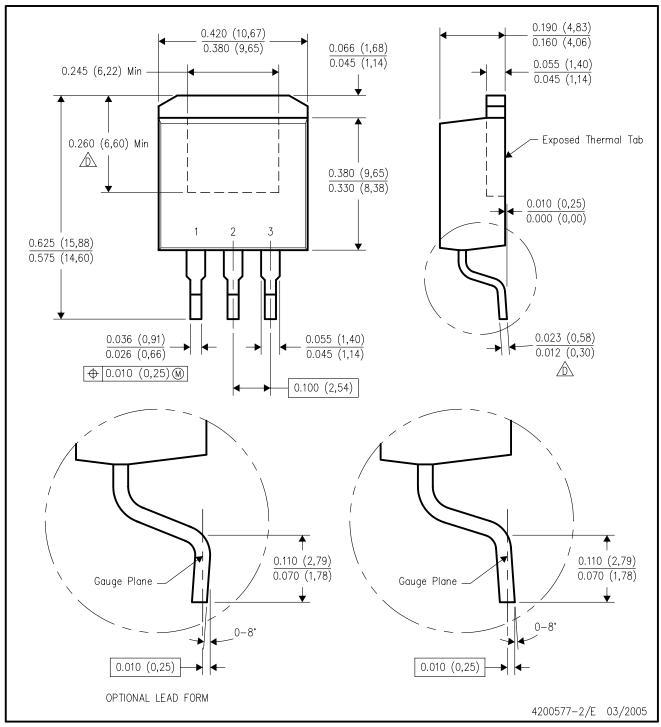
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC T0—220 variation AB, except minimum lead thickness, minimum exposed pad length, and maximum body length.



# KTT (R-PSFM-G3)

# PLASTIC FLANGE-MOUNT PACKAGE

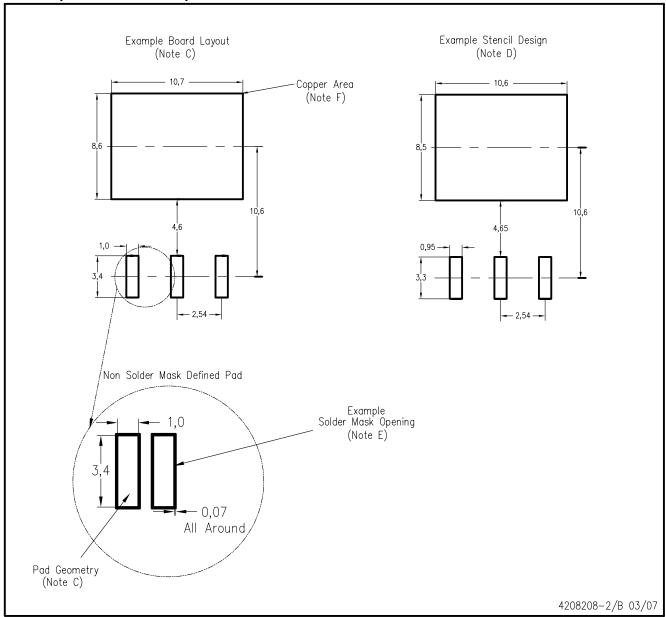


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.
- ∱ Falls within JEDEC TO-263 variation AA, except minimum lead thickness and minimum exposed pad length.



# KTT (R-PSFM-G3)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-SM-782 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release.

  Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
- F. This package is designed to be soldered to a thermal pad on the board. Refer to the Product Datasheet for specific thermal information, via requirements, and recommended thermal pad size. For thermal pad sizes larger than shown a solder mask defined pad is recommended in order to maintain the solderable pad geometry while increasing copper area.



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